

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

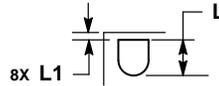
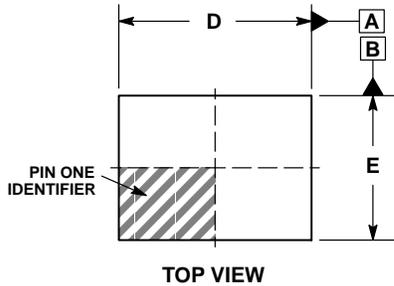
ON Semiconductor®



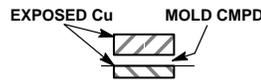
SCALE 4:1

XDFN8 1.6x1.2, 0.4P
CASE 711AS
ISSUE D

DATE 08 DEC 2015



DETAIL A
OPTIONAL
CONSTRUCTION

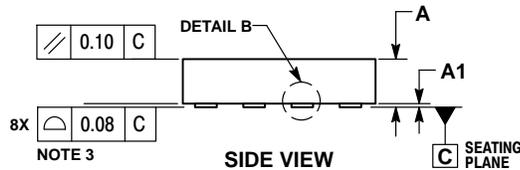


DETAIL B
OPTIONAL
CONSTRUCTION

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.300	0.375	0.450
A1	0.000	0.025	0.050
b	0.130	0.180	0.230
D	1.500	1.600	1.700
D2	1.200	1.300	1.400
E	1.100	1.200	1.300
E2	0.200	0.300	0.400
e	0.40 BSC		
L	0.150	0.200	0.250
L1	0.000	0.050	0.100



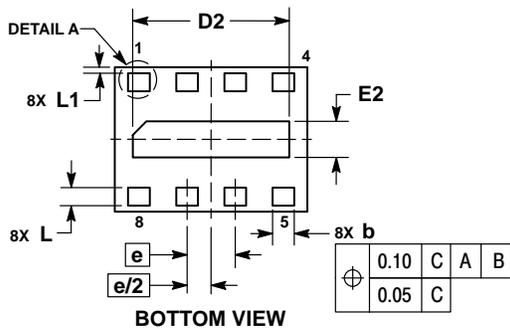
SIDE VIEW

GENERIC MARKING DIAGRAM*



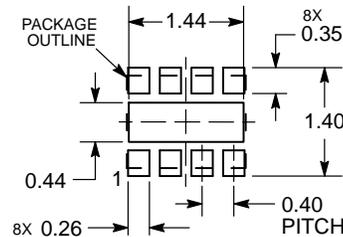
- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN8, 1.6X1.2, 0.4P	PAGE 1 OF 2

